ABSOCIATION CONNECTING ELECTRONICS (NDUSTRIES*) MAterial Compo © Copyright 2005. IP international and Pan-	C. Bannockł	ourn. Illinois. A	ll rights reserved untions.	under both	This docum level parts, t	ent is a declara	ation of the encompass	substances ses all low	s within the er level ma	e manufacture terials for wh	er listed it hich the m	em. Note: anufactur	if the item is an a er has engineering	ssembly with lower responsibility.	
				Form Type Distribute	*	Class 6 - RoHS Yes/No, Homogeneous Materia					als and Mfg Information				
Supplier Information															
Company name* Con			Company unique ID			Unique ID Authority					Response Date*				
onsemi											2023-06-08				
Contact Name	ontact Name Title - Contact				Р			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product Envi			viro Compliance			NA				Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Repr			presentative			Phone - Representative*				Email - Representative*					
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Item Number		ber Mfr Item Name			Effective Da	te Version	n	Manufacturing Site		1	Veight*	UOM	Unit Type	
	MC74L	MC74LVXT4053DG LOG CMOS		/ILTIPLXR ANALOG		2023-06-08			PH1		1	42.69	mg	Each	
Manufacturing Proccess Informati	on														
Terminal Plating / Grid Array Mat	Terminal Plating / Grid Array Material Terminal Base Alloy			J-STD-020 MSI	20 MSL Rating Peak Process Body Temperature Max Time at Pe					'ime at Peak '	k Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30		secon	ds 3				
Comments															
evel 1 - maximum time at peak temperatur	e during so	Idering is 10-3	0 seconds												
for more information regarding material c	omposition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless otherwise noted).										
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure		
Die	2.73	mg	Supplier	Silicon (Si)	7440-21-3		2.73	mg		
Die Attach	4.85	mg	Supplier	Silver (Ag)	7440-22-4		3.6375	mg		
			Supplier	Epoxy resins	129915-35-1		1.2125	mg		
Lead Frame 75	75.92	mg	Supplier	Silver (Ag)	7440-22-4		0.7592	mg		
			Supplier	Zinc (Zn)	7440-66-6		0.1518	mg		
			Supplier	Iron (Fe)	7439-89-6		1.9739	mg		
			Supplier	Copper (Cu)	7440-50-8		73.035	mg		
Mold Compound-Black	55.11	mg		Epoxy Phenol Resin	proprietary data		5.7866	mg		
			Supplier	Fused Silica (SiO2)	60676-86-0		49.3234	mg		
Plating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg		
Wire Bond - Au	0.35	mg	Supplier	Gold (Au)	7440-57-5		0.35	mg		

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 signar range of distribution unless otherwise noted)